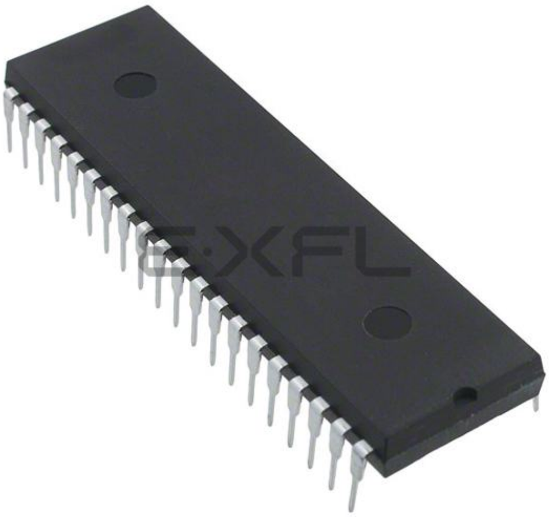


What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	33MHz
Connectivity	UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	33
Program Memory Size	4KB (2K x 16)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	232 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.600", 15.24mm)
Supplier Device Package	40-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic17c42a-33e-p

3.1 Clocking Scheme/Instruction Cycle

The clock input (from OSC1) is internally divided by four to generate four non-overlapping quadrature clocks, namely Q1, Q2, Q3, and Q4. Internally, the program counter (PC) is incremented every Q1, and the instruction is fetched from the program memory and latched into the instruction register in Q4. The instruction is decoded and executed during the following Q1 through Q4. The clocks and instruction execution flow are shown in Figure 3-3.

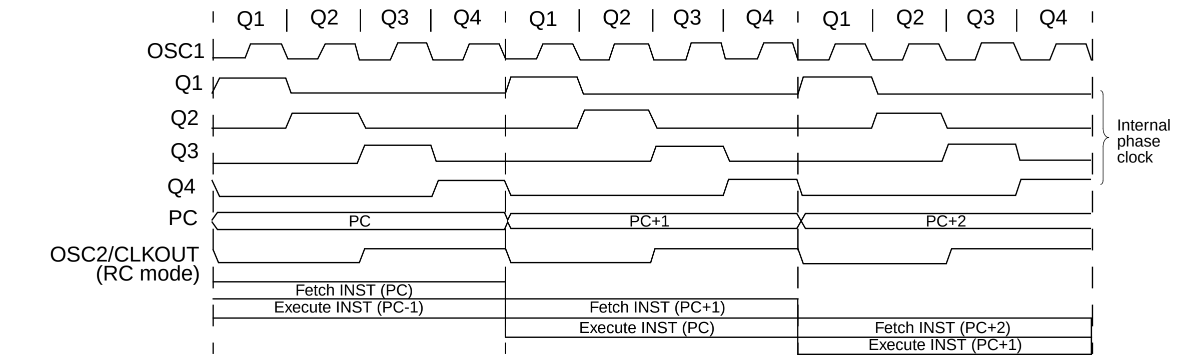
3.2 Instruction Flow/Pipelining

An "Instruction Cycle" consists of four Q cycles (Q1, Q2, Q3, and Q4). The instruction fetch and execute are pipelined such that fetch takes one instruction cycle while decode and execute takes another instruction cycle. However, due to the pipelining, each instruction effectively executes in one cycle. If an instruction causes the program counter to change (e.g. `GOTO`) then two cycles are required to complete the instruction (Example 3-2).

A fetch cycle begins with the program counter incrementing in Q1.

In the execution cycle, the fetched instruction is latched into the "Instruction Register (IR)" in cycle Q1. This instruction is then decoded and executed during the Q2, Q3, and Q4 cycles. Data memory is read during Q2 (operand read) and written during Q4 (destination write).

FIGURE 3-3: CLOCK/INSTRUCTION CYCLE

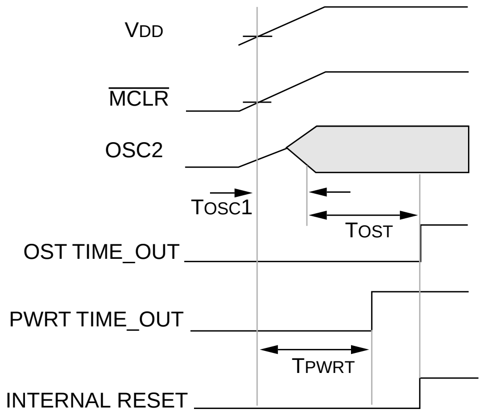


EXAMPLE 3-2: INSTRUCTION PIPELINE FLOW

	Tcy0	Tcy1	Tcy2	Tcy3	Tcy4	Tcy5
1. `MOVLW 55h`	Fetch 1	Execute 1				
2. `MOVWF PORTB`		Fetch 2	Execute 2			
3. `CALL SUB_1`			Fetch 3	Execute 3		
4. `BSF   PORTA, BIT3 (Forced NOP)`				Fetch 4	Flush	
5. `Instruction @ address SUB_1`					Fetch SUB_1	Execute SUB_1

All instructions are single cycle, except for any program branches. These take two cycles since the fetch instruction is "flushed" from the pipeline while the new instruction is being fetched and then executed.

FIGURE 4-5: OSCILLATOR START-UPTIME



This figure shows in greater detail the timings involved with the oscillator start-up timer. In this example the low frequency crystal start-up time is larger than power-up time (TPWRT).
Tosc1 = time for the crystal oscillator to react to an oscillation level detectable by the Oscillator Start-up Timer (ost).
TOST = 1024TOSC.

FIGURE 4-6: USING ON-CHIP POR

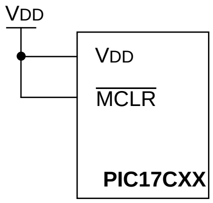
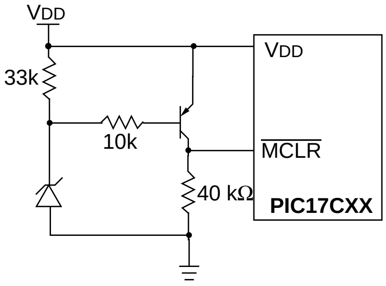
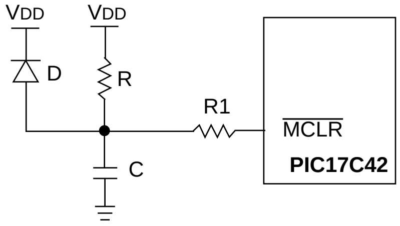


FIGURE 4-7: BROWN-OUT PROTECTION CIRCUIT 1



This circuit will activate reset when VDD goes below (Vz + 0.7V) where Vz = Zener voltage.

FIGURE 4-8: PIC17C42 EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)

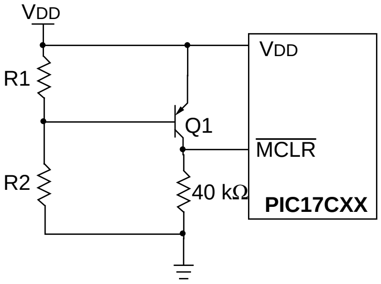


Note 1: An external Power-on Reset circuit is required only if VDD power-up time is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.

2: R < 40 kΩ is recommended to ensure that the voltage drop across R does not exceed 0.2V (max. leakage current spec. on the MCLR/VPP pin is 5 μA). A larger voltage drop will degrade VIH level on the MCLR/VPP pin.

3: R1 = 100Ω to 1 kΩ will limit any current flowing into MCLR from external capacitor C in the event of MCLR/VPP pin breakdown due to Electrostatic Discharge (ESD) or (Electrical Overstress) EOS.

FIGURE 4-9: BROWN-OUT PROTECTION CIRCUIT 2



This brown-out circuit is less expensive, albeit less accurate. Transistor Q1 turns off when VDD is below a certain level such that:

$$V_{DD} \bullet \frac{R1}{R1 + R2} = 0.7V$$

FIGURE 6-5: PIC17C42 REGISTER FILE MAP

Addr	Unbanked			
00h	INDF0			
01h	FSR0			
02h	PCL			
03h	PCLATH			
04h	ALUSTA			
05h	T0STA			
06h	CPUSTA			
07h	INTSTA			
08h	INDF1			
09h	FSR1			
0Ah	WREG			
0Bh	TMR0L			
0Ch	TMR0H			
0Dh	TBLPTRL			
0Eh	TBLPTRH			
0Fh	BSR			
	Bank 0	**Bank 1 [1]**	**Bank 2 [1]**	**Bank 3 [1]**
10h	PORTA	DDRC	TMR1	PW1DCL
11h	DDRB	PORTC	TMR2	PW2DCL
12h	PORTB	DDRD	TMR3L	PW1DCH
13h	RCSTA	PORTD	TMR3H	PW2DCH
14h	RCREG	DDRE	PR1	CA2L
15h	TXSTA	PORTE	PR2	CA2H
16h	TXREG	PIR	PR3L/CA1L	TCON1
17h	SPBRG	PIE	PR3H/CA1H	TCON2
18h 1Fh	General Purpose RAM			
20h FFh				

Note 1: SFR file locations 10h - 17h are banked. All other SFRs ignore the Bank Select Register (BSR) bits.

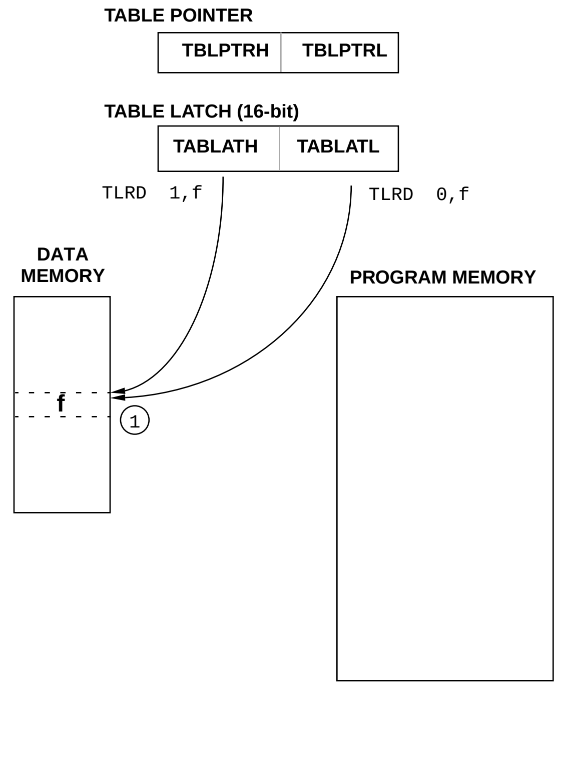
FIGURE 6-6: PIC17CR42/42A/43/R43/44 REGISTER FILE MAP

Addr	Unbanked			
00h	INDF0			
01h	FSR0			
02h	PCL			
03h	PCLATH			
04h	ALUSTA			
05h	T0STA			
06h	CPUSTA			
07h	INTSTA			
08h	INDF1			
09h	FSR1			
0Ah	WREG			
0Bh	TMR0L			
0Ch	TMR0H			
0Dh	TBLPTRL			
0Eh	TBLPTRH			
0Fh	BSR			
	Bank 0	**Bank 1 [1]**	**Bank 2 [1]**	**Bank 3 [1]**
10h	PORTA	DDRC	TMR1	PW1DCL
11h	DDRB	PORTC	TMR2	PW2DCL
12h	PORTB	DDRD	TMR3L	PW1DCH
13h	RCSTA	PORTD	TMR3H	PW2DCH
14h	RCREG	DDRE	PR1	CA2L
15h	TXSTA	PORTE	PR2	CA2H
16h	TXREG	PIR	PR3L/CA1L	TCON1
17h	SPBRG	PIE	PR3H/CA1H	TCON2
18h	PRODL			
19h	PRODH			
1Ah 1Fh	General Purpose RAM [2]			
20h FFh		General Purpose RAM [2]		

Note 1: SFR file locations 10h - 17h are banked. All other SFRs ignore the Bank Select Register (BSR) bits.

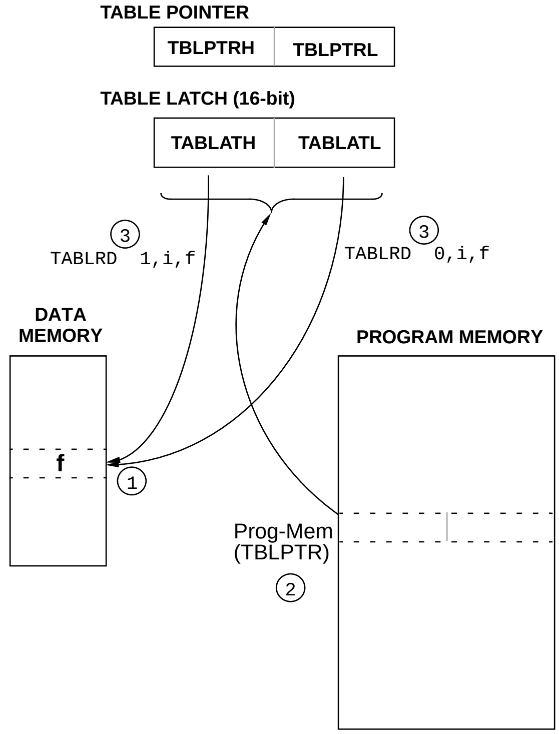
2: General Purpose Registers (GPR) locations 20h - FFh and 120h - 1FFh are banked. All other GPRs ignore the Bank Select Register (BSR) bits.

FIGURE 7-3: TLRD INSTRUCTION OPERATION



Note 1: 8-bit value, from TABLAT (16-bit) high or low byte, loaded into register 'f'.

FIGURE 7-4: TABLRD INSTRUCTION OPERATION



Note 1: 8-bit value, from TABLAT (16-bit) high or low byte, loaded into register 'f'.
2: 16-bit value at Program Memory (TBLPTR) loaded into TABLAT register.
3: If “i” = 1, then TBLPTR = TBLPTR + 1,
If “i” = 0, then TBLPTR is unchanged.

7.2 Table Writes to External Memory

Table writes to external memory are always two-cycle instructions. The second cycle writes the data to the external memory location. The sequence of events for an external memory write are the same for an internal write.

Note: If an interrupt is pending or occurs during the TABLWT, the two cycle table write completes. The RA0/INT, TMR0, or T0CKI interrupt flag is automatically cleared or the pending peripheral interrupt is acknowledged.

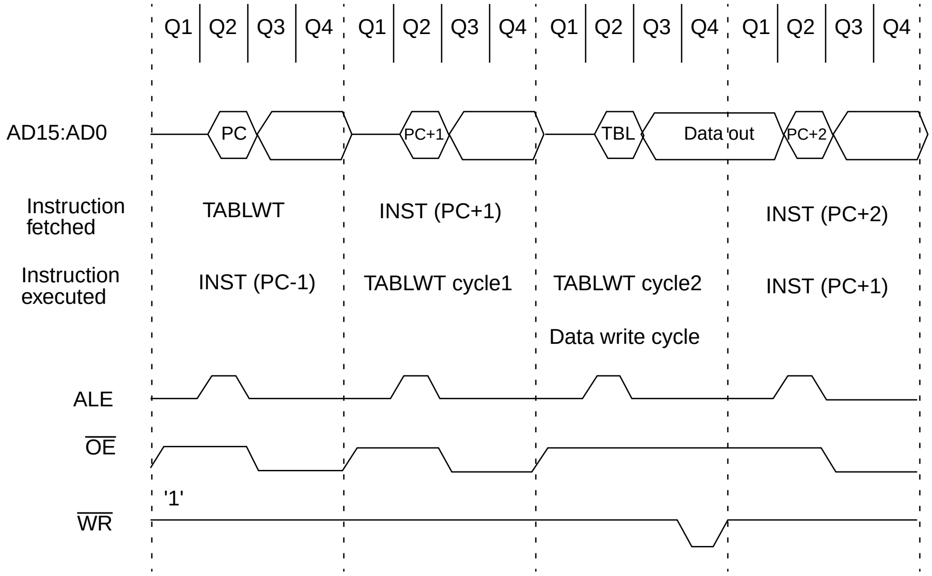
7.2.2 TABLE WRITE CODE

The "i" operand of the TABLWT instruction can specify that the value in the 16-bit TBLPTR register is automatically incremented for the next write. In Example 7-1, the TBLPTR register is not automatically incremented.

EXAMPLE 7-1: TABLE WRITE

```
CLRWDT                   ; Clear WDT
MOVLW   HIGH (TBL_ADDR) ; Load the Table
MOVWF   TBLPTRH         ;   address
MOVLW   LOW (TBL_ADDR)  ;
MOVWF   TBLPTRL         ;
MOVLW   HIGH (DATA)     ; Load HI byte
TLWT    1, WREG         ;   in TABLATCH
MOVLW   LOW (DATA)      ; Load LO byte
TABLWT  0,0,WREG        ;   in TABLATCH
                        ;   and write to
                        ;   program memory
                        ;   (Ext. SRAM)
```

FIGURE 7-5: TABLWT WRITE TIMING (EXTERNAL MEMORY)



Note: If external write GLINTD = '1', Enable bit = '1', '1' → Flag bit, Do table write. The highest pending interrupt is cleared.

10.0 OVERVIEW OF TIMER RESOURCES

The PIC17C4X has four timer modules. Each module can generate an interrupt to indicate that an event has occurred. These timers are called:

- Timer0 - 16-bit timer with programmable 8-bit prescaler
- Timer1 - 8-bit timer
- Timer2 - 8-bit timer
- Timer3 - 16-bit timer

For enhanced time-base functionality, two input Captures and two Pulse Width Modulation (PWM) outputs are possible. The PWMs use the TMR1 and TMR2 resources and the input Captures use the TMR3 resource.

10.1 Timer0 Overview

The Timer0 module is a simple 16-bit overflow counter. The clock source can be either the internal system clock (Fosc/4) or an external clock.

The Timer0 module also has a programmable prescaler option. The PS3:PS0 bits (T0STA<4:1>) determine the prescaler value. TMR0 can increment at the following rates: 1:1, 1:2, 1:4, 1:8, 1:16, 1:32, 1:64, 1:128, 1:256.

When TImer0's clock source is an external clock, the Timer0 module can be selected to increment on either the rising or falling edge.

Synchronization of the external clock occurs after the prescaler. When the prescaler is used, the external clock frequency may be higher then the device's frequency. The maximum frequency is 50 MHz, given the high and low time requirements of the clock.

10.2 Timer1 Overview

The TImer0 module is an 8-bit timer/counter with an 8-bit period register (PR1). When the TMR1 value rolls over from the period match value to 0h, the TMR1IF flag is set, and an interrupt will be generated when enabled. In counter mode, the clock comes from the RB4/TCLK12 pin, which can also be selected to be the clock for the Timer2 module.

TMR1 can be concatenated to TMR2 to form a 16-bit timer. The TMR1 register is the LSB and TMR2 is the MSB. When in the 16-bit timer mode, there is a corresponding 16-bit period register (PR2:PR1). When the TMR2:TMR1 value rolls over from the period match value to 0h, the TMR1IF flag is set, and an interrupt will be generated when enabled.

10.3 Timer2 Overview

The TMR2 module is an 8-bit timer/counter with an 8-bit period register (PR2). When the TMR2 value rolls over from the period match value to 0h, the TMR2IF flag is set, and an interrupt will be generated when enabled. In counter mode, the clock comes from the RB4/TCLK12 pin, which can also be selected to be the clock for the TMR1 module.

TMR1 can be concatenated to TMR2 to form a 16-bit timer. The TMR2 register is the MSB and TMR1 is the LSB. When in the 16-bit timer mode, there is a corresponding 16-bit period register (PR2:PR1). When the TMR2:TMR1 value rolls over from the period match value to 0h, the TMR1IF flag is set, and an interrupt will be generated when enabled.

10.4 Timer3 Overview

The TImer3 module is a 16-bit timer/counter with a 16-bit period register. When the TMR3H:TMR3L value rolls over to 0h, the TMR3IF bit is set and an interrupt will be generated when enabled. In counter mode, the clock comes from the RB5/TCLK3 pin.

When operating in the dual capture mode, the period registers become the second 16-bit capture register.

10.5 Role of the Timer/Counters

The timer modules are general purpose, but have dedicated resources associated with them. TImer1 and Timer2 are the time-bases for the two Pulse Width Modulation (PWM) outputs, while Timer3 is the time-base for the two input captures.

11.1 Timer0 Operation

When the T0CS (T0STA<5>) bit is set, TMR0 increments on the internal clock. When T0CS is clear, TMR0 increments on the external clock (RA1/T0CKI pin). The external clock edge can be configured in software. When the T0SE (T0STA<6>) bit is set, the timer will increment on the rising edge of the RA1/T0CKI pin. When T0SE is clear, the timer will increment on the falling edge of the RA1/T0CKI pin. The prescaler can be programmed to introduce a prescale of 1:1 to 1:256. The timer increments from 0000h to FFFFh and rolls over to 0000h. On overflow, the TMR0 Interrupt Flag bit (T0IF) is set. The TMR0 interrupt can be masked by clearing the corresponding TMR0 Interrupt Enable bit (T0IE). The TMR0 Interrupt Flag bit (T0IF) is automatically cleared when vectoring to the TMR0 interrupt vector.

11.2 Using Timer0 with External Clock

When the external clock input is used for Timer0, it is synchronized with the internal phase clocks. Figure 11-3 shows the synchronization of the external clock. This synchronization is done after the prescaler. The output of the prescaler (PSOUT) is sampled twice in every instruction cycle to detect a rising or a falling edge. The timing requirements for the external clock are detailed in the electrical specification section for the desired device.

11.2.1 DELAY FROM EXTERNAL CLOCK EDGE

Since the prescaler output is synchronized with the internal clocks, there is a small delay from the time the external clock edge occurs to the time TMR0 is actually incremented. Figure 11-3 shows that this delay is between 3TOSC and 7TOSC. Thus, for example, measuring the interval between two edges (e.g. period) will be accurate within ±4TOSC (±121 ns @ 33 MHz).

FIGURE 11-2: TIMER0 MODULE BLOCK DIAGRAM

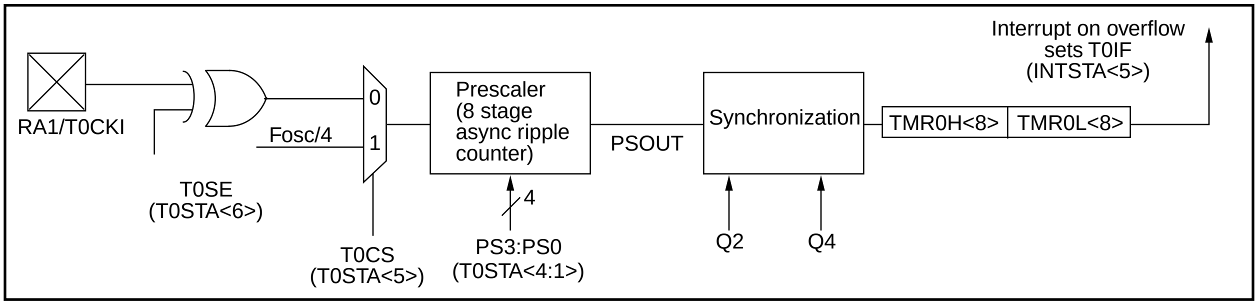
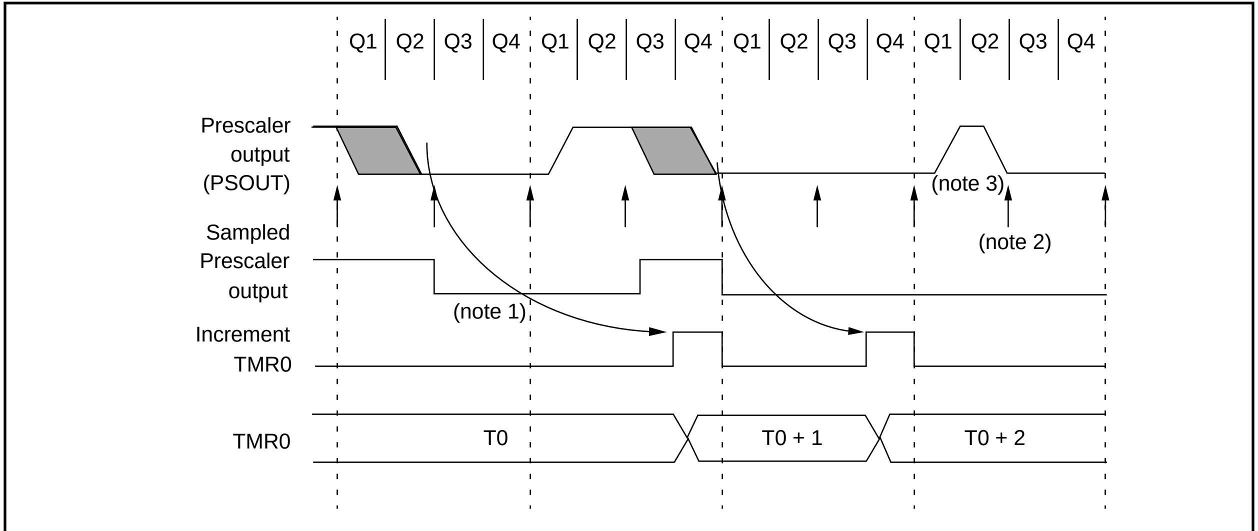
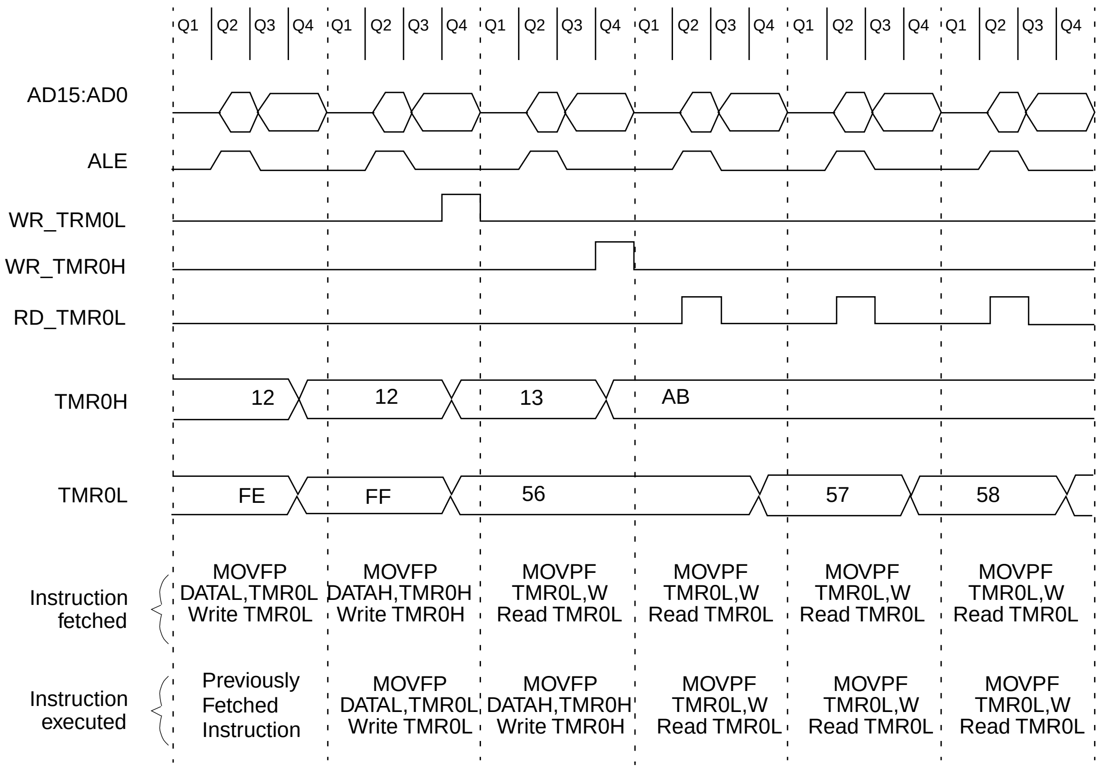


FIGURE 11-3: TMR0 TIMING WITH EXTERNAL CLOCK (INCREMENT ON FALLING EDGE)



Note 1: The delay from the T0CKI edge to the TMR0 increment is 3Tosc to 7Tosc.
2: ↑ = PSOUT is sampled here.
3: The PSOUT high time is too short and is missed by the sampling circuit.

FIGURE 11-5: TMR0 READ/WRITE IN TIMER MODE



In this example, old TMR0 value is 12FEh, new value of AB56h is written.

TABLE 11-1: REGISTERS/BITS ASSOCIATED WITH TIMER0

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Value on all other resets (Note1)
05h, Unbanked	T0STA	INTEDG	T0SE	T0CS	PS3	PS2	PS1	PS0	—	0000 000-	0000 000-
06h, Unbanked	CPUSTA	—	—	STKAV	GLINTD	$\overline{TO}$	$\overline{PD}$	—	—	--11 11--	--11 qq--
07h, Unbanked	INTSTA	PEIF	T0CKIF	T0IF	INTF	PEIE	T0CKIE	T0IE	INTE	0000 0000	0000 0000
0Bh, Unbanked	TMR0L	TMR0 register; low byte								xxxx xxxx	uuuu uuuu
0Ch, Unbanked	TMR0H	TMR0 register; high byte								xxxx xxxx	uuuu uuuu

Legend: x = unknown, u = unchanged, - = unimplemented read as a '0', q - value depends on condition, Shaded cells are not used by Timer0.
Note 1: Other (non power-up) resets include: external reset through $\overline{MCLR}$ and the Watchdog Timer Reset.

14.1 Configuration Bits

The PIC17CXX has up to seven configuration locations (Table 14-1). These locations can be programmed (read as '0') or left unprogrammed (read as '1') to select various device configurations. Any write to a configuration location, regardless of the data, will program that configuration bit. A `TABLWT` instruction is required to write to program memory locations. The configuration bits can be read by using the `TABLRD` instructions. Reading any configuration location between FE00h and FE07h will read the low byte of the configuration word (Figure 14-1) into the TABLATL register. The TABLATH register will be FFh. Reading a configuration location between FE08h and FE0Fh will read the high byte of the configuration word into the TABLATL register. The TABLATH register will be FFh.

Addresses FE00h thorough FE0Fh are only in the program memory space for microcontroller and code protected microcontroller modes. A device programmer will be able to read the configuration word in any processor mode. See programming specifications for more detail.

TABLE 14-1: CONFIGURATION LOCATIONS

Bit	Address
FOSC0	FE00h
FOSC1	FE01h
WDTPS0	FE02h
WDTPS1	FE03h
PM0	FE04h
PM1	FE06h
PM2 [(1)]	FE0Fh [(1)]

Note 1: This location does not exist on the PIC17C42.

Note: When programming the desired configuration locations, they must be programmed in ascending order. Starting with address FE00h.

14.2 Oscillator Configurations

14.2.1 OSCILLATOR TYPES

The PIC17CXX can be operated in four different oscillator modes. The user can program two configuration bits (FOSC1:FOSC0) to select one of these four modes:

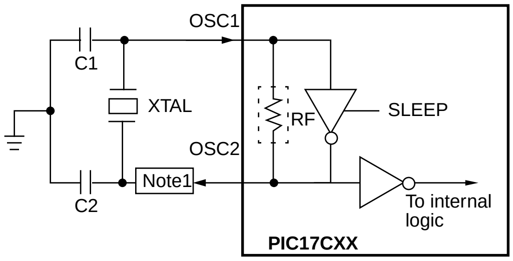
- LF: Low Power Crystal
- XT: Crystal/Resonator
- EC: External Clock Input
- RC: Resistor/Capacitor

14.2.2 CRYSTAL OSCILLATOR / CERAMIC RESONATORS

In XT or LF modes, a crystal or ceramic resonator is connected to the OSC1/CLKIN and OSC2/CLKOUT pins to establish oscillation (Figure 14-2). The PIC17CXX Oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications.

For frequencies above 20 MHz, it is common for the crystal to be an overtone mode crystal. Use of overtone mode crystals require a tank circuit to attenuate the gain at the fundamental frequency. Figure 14-3 shows an example of this.

FIGURE 14-2: CRYSTAL OR CERAMIC RESONATOR OPERATION (XT OR LF OSC CONFIGURATION)



See Table 14-2 and Table 14-3 for recommended values of C1 and C2.

Note 1: A series resistor may be required for AT strip cut crystals.

DCFSNZ Decrement f, skip if not 0

Syntax: [*label*] DCFSNZ f,d

Operands: $0 \le f \le 255$
$d \in [0,1]$

Operation: (f) – 1 → (dest);
skip if not 0

Status Affected: None

Encoding:

0010	011d	ffff	ffff

Description: The contents of register 'f' are decremented. If 'd' is 0 the result is placed in WREG. If 'd' is 1 the result is placed back in register 'f'.

If the result is not 0, the next instruction, which is already fetched, is discarded, and an NOP is executed instead making it a two-cycle instruction.

Words: 1

Cycles: 1(2)

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write to destination

If skip:

Q1	Q2	Q3	Q4
Forced NOP	NOP	Execute	NOP

Example:

```
HERE     DCFSNZ  TEMP, 1
ZERO     :
NZERO    :
```

Before Instruction
TEMP_VALUE = ?

After Instruction
TEMP_VALUE = TEMP_VALUE - 1,
If TEMP_VALUE = 0;
PC = Address (ZERO)
If TEMP_VALUE ≠ 0;
PC = Address (NZERO)

GOTO Unconditional Branch

Syntax: [*label*] GOTO k

Operands: $0 \le k \le 8191$

Operation: k → PC<12:0>;
k<12:8> → PCLATH<4:0>,
PC<15:13> → PCLATH<7:5>

Status Affected: None

Encoding:

110k	kkkk	kkkk	kkkk

Description: GOTO allows an unconditional branch anywhere within an 8K page boundary. The thirteen bit immediate value is loaded into PC bits <12:0>. Then the upper eight bits of PC are loaded into PCLATH. GOTO is always a two-cycle instruction.

Words: 1

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'<7:0>	Execute	NOP
Forced NOP	NOP	Execute	NOP

Example: `GOTO THERE`

After Instruction
PC = Address (THERE)

MOVPF Move p to f

Syntax: [*label*] MOVPF p,f

Operands: 0 ≤ f ≤ 255
0 ≤ p ≤ 31

Operation: (p) → (f)

Status Affected: Z

Encoding:

`010p`	`pppp`	`ffff`	`ffff`

Description: Move data from data memory location 'p' to data memory location 'f'. Location 'f' can be anywhere in the 256 byte data space (00h to FFh) while 'p' can be 00h to 1Fh.

Either 'p' or 'f' can be WREG (a useful special situation).

`MOVPF` is particularly useful for transferring a peripheral register (e.g. the timer or an I/O port) to a data memory location. Both 'f' and 'p' can be indirectly addressed.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'p'	Execute	Write register 'f'

Example: `MOVPF REG1, REG2`

Before Instruction

REG1	=	0x11
REG2	=	0x33

After Instruction

REG1	=	0x11
REG2	=	0x11

MOVWF Move WREG to f

Syntax: [*label*] MOVWF f

Operands: 0 ≤ f ≤ 255

Operation: (WREG) → (f)

Status Affected: None

Encoding:

`0000`	`0001`	`ffff`	`ffff`

Description: Move data from WREG to register 'f'. Location 'f' can be anywhere in the 256 word data space.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write register 'f'

Example: `MOVWF REG`

Before Instruction

WREG	=	0x4F
REG	=	0xFF

After Instruction

WREG	=	0x4F
REG	=	0x4F

RLNCF — Rotate Left f (no carry)

Syntax: [*label*] RLNCF f,d

Operands: 0 ≤ f ≤ 255
d ∈ [0,1]

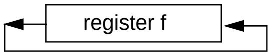
Operation: f<n> → d<n+1>;
f<7> → d<0>

Status Affected: None

Encoding:

`0010`	`001d`	`ffff`	`ffff`

Description: The contents of register 'f' are rotated one bit to the left. If 'd' is 0 the result is placed in WREG. If 'd' is 1 the result is stored back in register 'f'.



Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write to destination

Example: `RLNCF REG, 1`

Before Instruction

```
C    =  0
REG  =  1110 1011
```

After Instruction

```
C    =
REG  =  1101 0111
```

RRCF — Rotate Right f through Carry

Syntax: [*label*] RRCF f,d

Operands: 0 ≤ f ≤ 255
d ∈ [0,1]

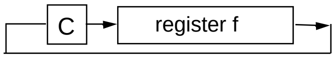
Operation: f<n> → d<n-1>;
f<0> → C;
C → d<7>

Status Affected: C

Encoding:

`0001`	`100d`	`ffff`	`ffff`

Description: The contents of register 'f' are rotated one bit to the right through the Carry Flag. If 'd' is 0 the result is placed in WREG. If 'd' is 1 the result is placed back in register 'f'.



Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write to destination

Example: `RRCF REG1,0`

Before Instruction

```
REG1  =  1110 0110
C     =  0
```

After Instruction

```
REG1  =  1110 0110
WREG  =  0111 0011
C     =  0
```

SWAPF Swap f

Syntax: [*label*] SWAPF f,d

Operands: $0 \le f \le 255$
$d \in [0,1]$

Operation: f<3:0> → dest<7:4>;
f<7:4> → dest<3:0>

Status Affected: None

Encoding:

`0001`	`110d`	`ffff`	`ffff`

Description: The upper and lower nibbles of register 'f' are exchanged. If 'd' is 0 the result is placed in WREG. If 'd' is 1 the result is placed in register 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write to destination

Example: `SWAPF REG, 0`

Before Instruction
REG = 0x53

After Instruction
REG = 0x35

TABLRD Table Read

Syntax: [*label*] TABLRD t,i,f

Operands: $0 \le f \le 255$
$i \in [0,1]$
$t \in [0,1]$

Operation:
If t = 1,
  TBLATH → f;
If t = 0,
  TBLATL → f;
  Prog Mem (TBLPTR) → TBLAT;
If i = 1,
  TBLPTR + 1 → TBLPTR

Status Affected: None

Encoding:

`1010`	`10ti`	`ffff`	`ffff`

Description:

1. A byte of the table latch (TBLAT) is moved to register file 'f'.
   If t = 0: the high byte is moved;
   If t = 1: the low byte is moved
2. Then the contents of the program memory location pointed to by the 16-bit Table Pointer (TBLPTR) is loaded into the 16-bit Table Latch (TBLAT).
3. If i = 1: TBLPTR is incremented;
   If i = 0: TBLPTR is not incremented

Words: 1

Cycles: 2 (3 cycle if f = PCL)

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register TBLATH or TBLATL	Execute	Write register 'f'

Applicable Devices	42	R42	42A	43	R43	44

FIGURE 18-4: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD

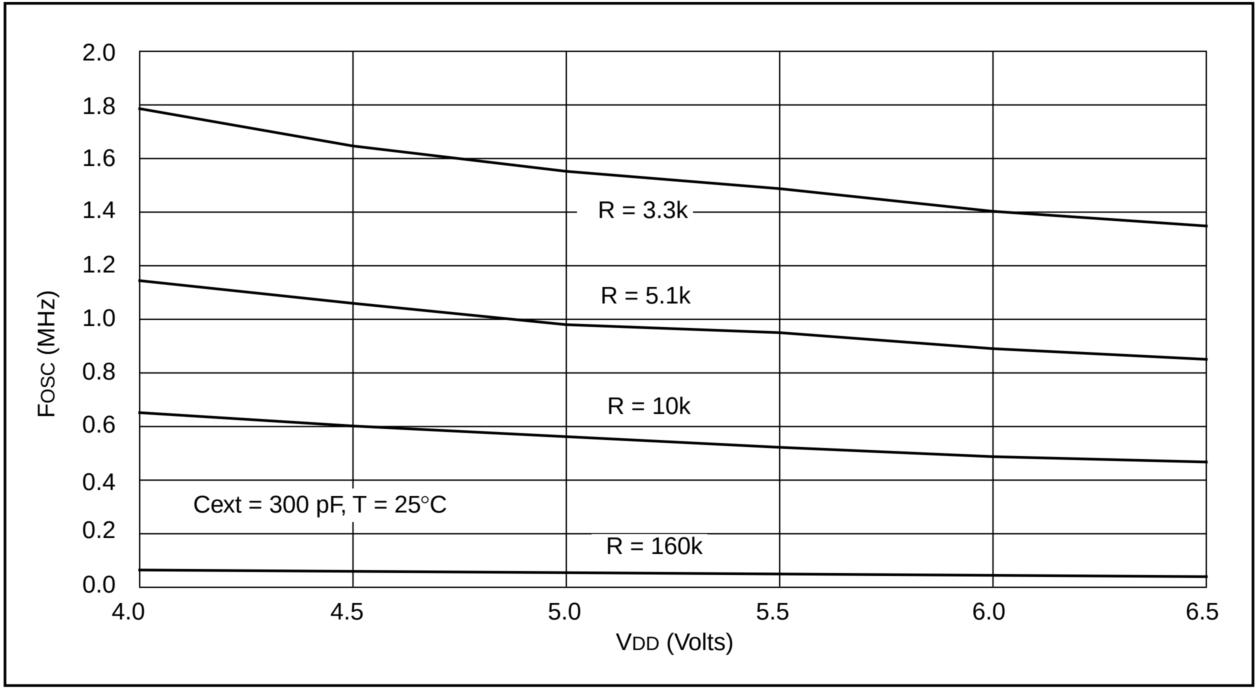


TABLE 18-2: RC OSCILLATOR FREQUENCIES

Cext	Rext	Average Fosc @ 5V, 25°C	
22 pF	10k	3.33 MHz	± 12%
	100k	353 kHz	± 13%
100 pF	3.3k	3.54 MHz	± 10%
	5.1k	2.43 MHz	± 14%
	10k	1.30 MHz	± 17%
	100k	129 kHz	± 10%
300 pF	3.3k	1.54 MHz	± 14%
	5.1k	980 kHz	± 12%
	10k	564 kHz	± 16%
	160k	35 kHz	± 18%

NOTES:

Applicable Devices	42	R42	42A	43	R43	44

19.0 PIC17CR42/42A/43/R43/44 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Ambient temperature under bias	-55 to +125˚C
Storage temperature	-65˚C to +150˚C
Voltage on V_{DD} with respect to V_{SS}	0 to +7.5V
Voltage on $\overline{MCLR}$ with respect to V_{SS} (Note 2)	-0.6V to +14V
Voltage on RA2 and RA3 with respect to V_{SS}	-0.6V to +14V
Voltage on all other pins with respect to V_{SS}	-0.6V to V_{DD} + 0.6V
Total power dissipation (Note 1)	1.0W
Maximum current out of V_{SS} pin(s) - total	250 mA
Maximum current into V_{DD} pin(s) - total	200 mA
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{DD}$)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{DD}$)	±20 mA
Maximum output current sunk by any I/O pin (except RA2 and RA3)	35 mA
Maximum output current sunk by RA2 or RA3 pins	60 mA
Maximum output current sourced by any I/O pin	20 mA
Maximum current sunk by PORTA and PORTB (combined)	150 mA
Maximum current sourced by PORTA and PORTB (combined)	100 mA
Maximum current sunk by PORTC, PORTD and PORTE (combined)	150 mA
Maximum current sourced by PORTC, PORTD and PORTE (combined)	100 mA

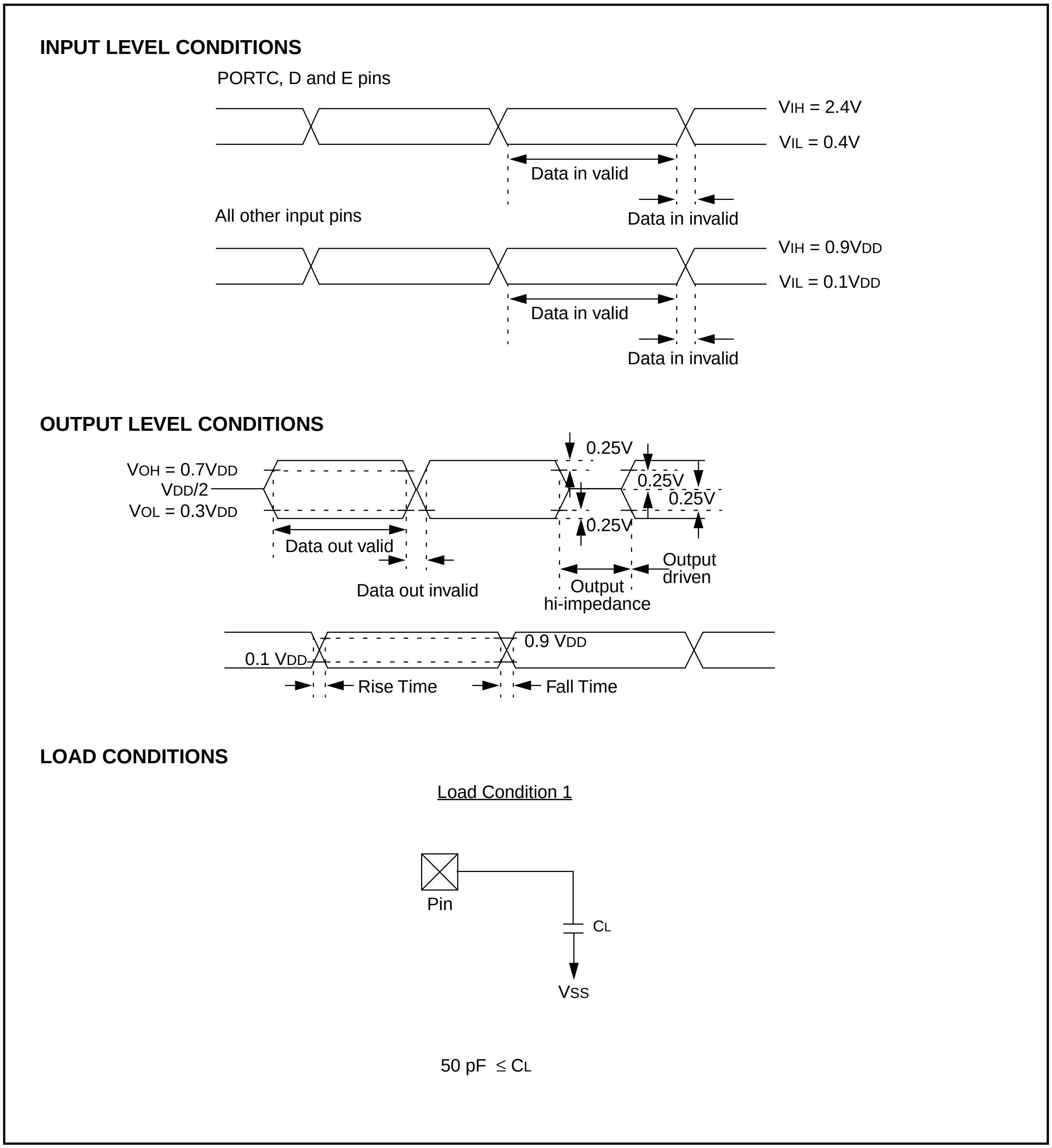
Note 1: Power dissipation is calculated as follows: Pdis = $V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD}-V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$

Note 2: Voltage spikes below V_{SS} at the $\overline{MCLR}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the $\overline{MCLR}$ pin rather than pulling this pin directly to V_{SS}.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

FIGURE 19-1: PARAMETER MEASUREMENT INFORMATION

All timings are measure between high and low measurement points as indicated in the figures below.



Applicable Devices	42	R42	42A	43	R43	44

20.0 PIC17CR42/42A/43/R43/44 DC AND AC CHARACTERISTICS

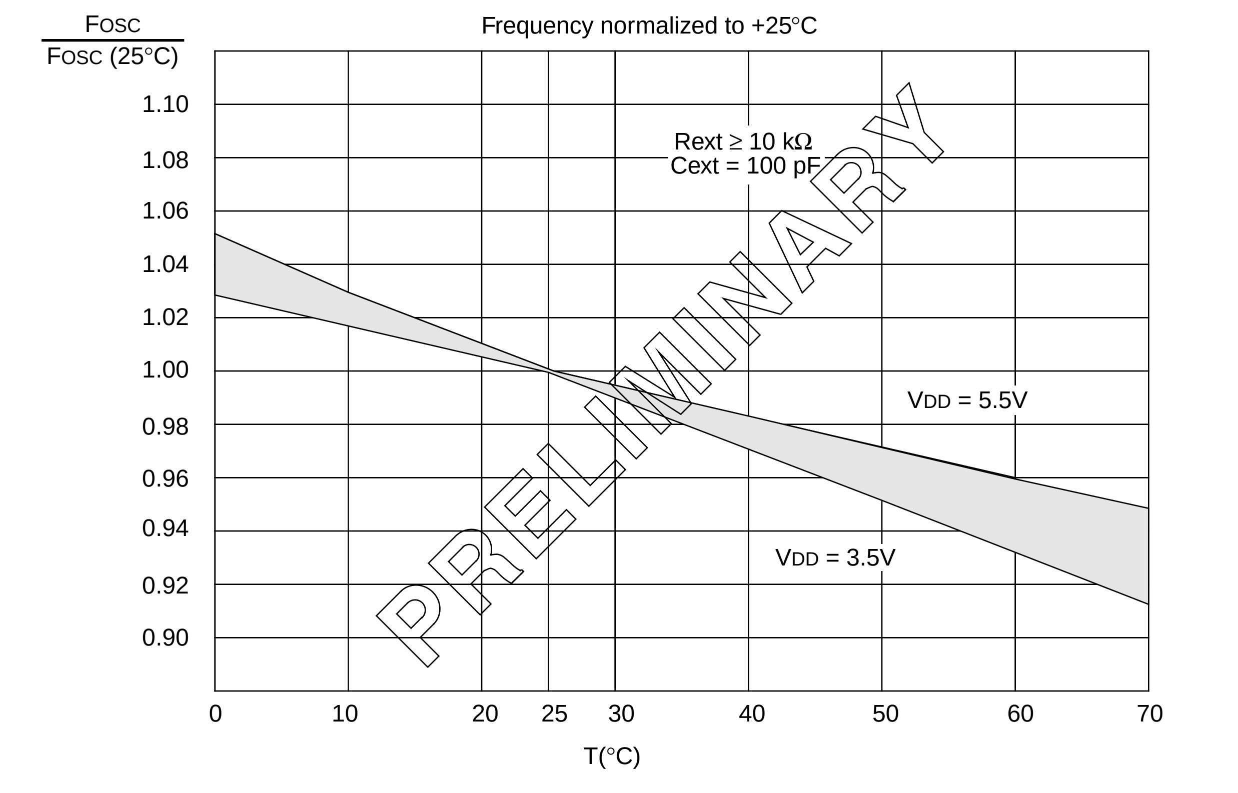
The graphs and tables provided in this section are for design guidance and are not tested nor guaranteed. In some graphs or tables the data presented is outside specified operating range (e.g. outside specified VDD range). This is for information only and devices are ensured to operate properly only within the specified range.

The data presented in this section is a statistical summary of data collected on units from different lots over a period of time. "Typical" represents the mean of the distribution while "max" or "min" represents (mean + 3σ) and (mean - 3σ) respectively where σ is standard deviation.

TABLE 20-1: PIN CAPACITANCE PER PACKAGE TYPE

Pin Name	Typical Capacitance (pF)			
	40-pin DIP	44-pin PLCC	44-pin MQFP	44-pin TQFP
All pins, except $\overline{\text{MCLR}}$, VDD, and VSS	10	10	10	10
$\overline{\text{MCLR}}$ pin	20	20	20	20

FIGURE 20-1: TYPICAL RC OSCILLATOR FREQUENCY vs. TEMPERATURE



PIC17C4X Product Identification System

To order or to obtain information, e.g., on pricing or delivery, please use the listed part numbers, and refer to the factory or the listed sales offices.

PART NO. – XX X /XX XXX

Pattern:	QTP, SQTP, ROM Code (factory specified) or Special Requirements. Blank for OTP and Windowed devices		
Package:	P	=	PDIP
	JW	=	Windowed CERDIP
	P	=	PDIP (600 mil)
	PQ	=	MQFP
	PT	=	TQFP
	L	=	PLCC
Temperature Range:	–	=	0˚C to +70˚C
	I	=	–40˚C to +85˚C
Frequency Range:	08	=	8 MHz
	16	=	16 MHz
	25	=	25 Mhz
	33	=	33 Mhz
Device:	PIC17C44	:	Standard Vdd range
	PIC17C44T	:	(Tape and Reel)
	PIC17LC44	:	Extended Vdd range

Examples

a) PIC17C42 – 16/P Commercial Temp., PDIP package, 16 MHZ, normal VDD limits

b) PIC17LC44 – 08/PT Commercial Temp., TQFP package, 8MHz, extended VDD limits

c) PIC17C43 – 25I/P Industrial Temp., PDIP package, 25 MHz, normal VDD limits

Sales and Support

Products supported by a preliminary Data Sheet may possibly have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

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2.The Microchip Corporate Literature Center U.S. FAX: (602) 786-7277

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